

What is claimed is;

1. Washing liquid for a semiconductor substrate having a copper wiring, comprising a basic compound and at least one selected from the group consisting of sugar alcohols and saccharides.

2. The washing liquid according to Claim 1, wherein the sugar alcohols are mannitol.

3. The washing liquid according to Claim 1, wherein the basic compound is a quaternary ammonium hydroxide.

4. The washing liquid according to Claim 1, wherein the concentration of the sugar alcohol is from 0.01 to 5 wt%.

5. The washing liquid according to Claim 1, wherein the concentration of the basic compound is from 0.05 to 1 wt%.

6. A method of producing a semiconductor device, comprising a step of forming a copper wiring by chemical mechanical polishing and washing with washing liquid for a semiconductor substrate comprising a basic compound and at least one selected from the group consisting of sugar alcohols and saccharides.

7. The method according to Claim 6, wherein the sugar alcohols are mannitol.

8. The method according to Claim 6, wherein the basic compound is a quaternary ammonium hydroxide.

9 The method according to Claim 6, wherein the concentration of the sugar alcohol is from 0.01 to 5 wt%.

10. The method according to Claim 6, wherein the concentration of the basic compound is from 0.05 to 1 wt%.